

StannoPure[®] PF

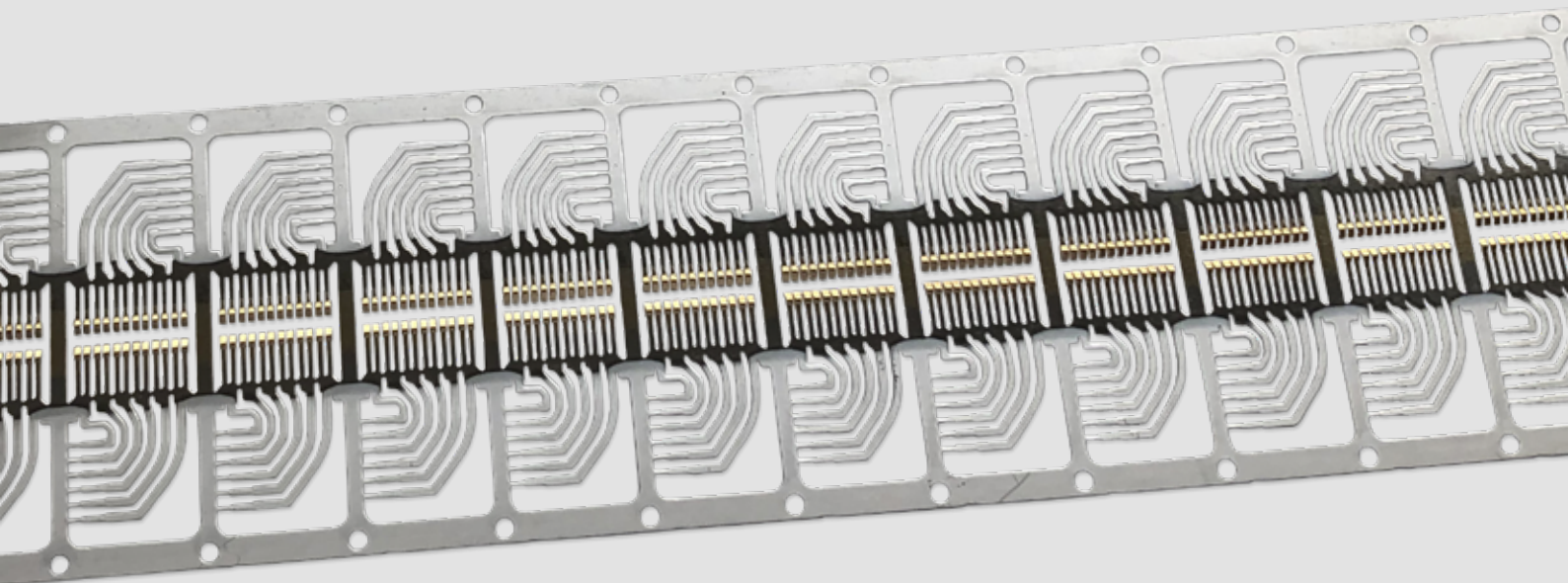
Electrolytic Sn process



Electronics

Functional electronic coatings

atotech.com



High speed Tin process for lead frames and connectors for a perfect coverage at every spot

100

percent coverage

Stannopure[®] PF

Stannopure[®] PF is a high speed MSA based pure Tin electrolyte for lead frames, connectors and wires. With its perfect tin coverage over the entire current density range Stannopure[®] PF is designed to plate even the most difficult connector and lead frame designs. Plating Cu leads near the package body with Sn has never been so easy.

Electrolytic Sn process

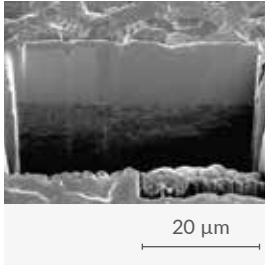
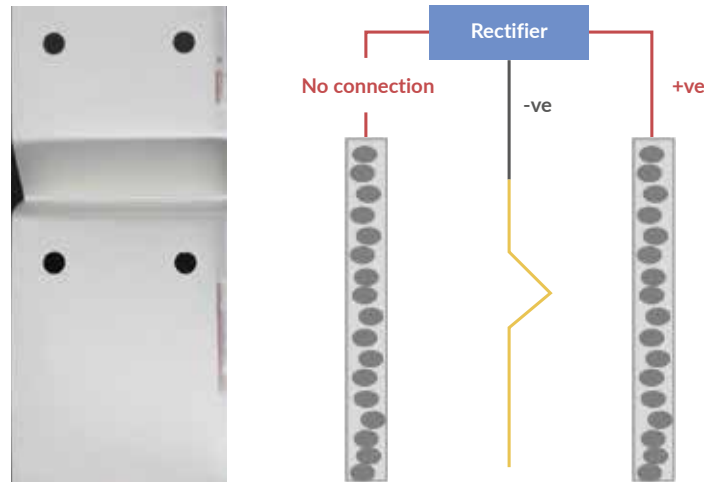


Figure 1:
Grain structure

Coverage test at 20 ASD



Features and benefits

- High speed deposition of up to 25 ASD
- Low MSA
- No oil out
- Perfect solderability with all lead-free and lead containing solders
- Perfect coverage over entire CD range even at lowest CD
- Low whisker propensity
- Developed for all modern plating tools

